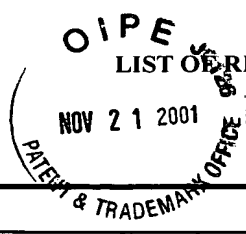


|   |  |  |  |                                   |  |                               |  |
|---|--|--|--|-----------------------------------|--|-------------------------------|--|
|  <b>LIST OF REFERENCES CITED BY APPLICANT</b><br>(Use several sheets if necessary) |  |  |  | ATTY. DOCKET NO.<br>9818-0055-999 |  | APPLICATION NO.<br>09/938,075 |  |
|   |  |  |  | APPLICANT<br>Mohammad Eslamy      |  |                               |  |
|   |  |  |  | FILING DATE<br>August 23, 2001    |  | GROUP<br>2811                 |  |

| U.S. PATENT DOCUMENTS |    |                 |      |      |       |          |                                 |
|-----------------------|----|-----------------|------|------|-------|----------|---------------------------------|
| *EXAMINER<br>INITIAL  | AA | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE<br>(IF APPROPRIATE) |
|                       | AA |                 |      |      |       |          |                                 |
|                       | AB |                 |      |      |       |          |                                 |
|                       | AC |                 |      |      |       |          |                                 |
|                       | AD |                 |      |      |       |          |                                 |
|                       | AE |                 |      |      |       |          |                                 |
|                       | AF |                 |      |      |       |          |                                 |
|                       | AG |                 |      |      |       |          |                                 |
|                       | AH |                 |      |      |       |          |                                 |
|                       | AI |                 |      |      |       |          |                                 |

| FOREIGN PATENT DOCUMENTS |    |                 |      |         |       |          |             |
|--------------------------|----|-----------------|------|---------|-------|----------|-------------|
|                          |    | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION |
|                          |    |                 |      |         |       |          | YES NO      |
|                          | AJ |                 |      |         |       |          |             |
|                          | AK |                 |      |         |       |          |             |
|                          | AL |                 |      |         |       |          |             |
|                          | AM |                 |      |         |       |          |             |
|                          | AN |                 |      |         |       |          |             |

| OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.) |    |  |
|---|----|--|
| JN  | AO | R. Tummala <i>et al.</i> , MICROELECTRONICS PACKAGING HANDBOOK, PART II, SEMICONDUCTOR PACKAGING, (Second Edition, 1997) pp. 78-81, 165-169 and 305-311. |
|   | AP |  |
|   | AQ |  |

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|----------------------------------|----------------------------------|
| EXAMINER<br><b>JOSEPH NEUVEN</b> | DATE CONSIDERED<br><b>3/7/02</b> |
|----------------------------------|----------------------------------|

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.